Application no. 09/251,183

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March 20, 2001

Washington, D.C. 20231

FROM:

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SUBJECT:

Serial #:

09/251,183

File Date:

2/17/99

Inventor:

Lin, M.S.

Examiner:

J. Garcia

Art Unit:

2823

Title:

Top Layers of Metal for High Performance IC's

. 03/29/2001 TDAWKINS 00000003 190033 09251183 RESPONSE TO OFFICE ACTION

01 FC:102

160.00 CH

This is in response to the office action dated Oct. 20, 2000. Please amend the above identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231 on March 20, 2001.

Signature

Stephen B. Ackerman, Reg. No. 37,761

Date:

3/20/01